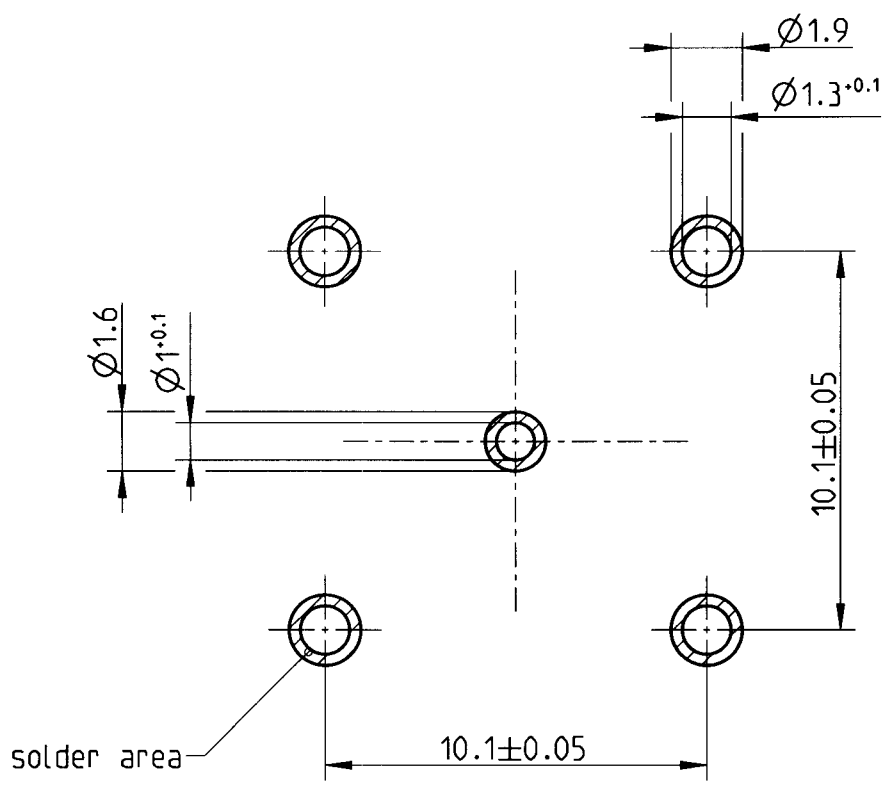


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Leiterplatten-Layout
 PCB layout
 B 32



A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector. Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimum solderability of the connector. In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

Formzahl: TIC_EB_06_Pf_A_Einzelteil
 Date: AX_EINZELTIL_003.FRM
 Version: 1.1

ISO-Projektion
 Methode E
 -METRIC-

Rosenberger Hochfrequenztechnik 84526 Tittmoning Pro/ENGINEER		<i>general tolerance</i> ISO 2768 RN 006-01 m-H dimensions <0,5 and symmetry		<i>scale:</i> 5:1	<i>weight(g):</i> <i>surface(mm²):</i>
		<i>material:</i>		Leiterplatten-Layout PCB layout	
<i>date</i> <i>name</i>		<i>title:</i>			
<i>drawn</i> 15.02.2001 A_Nobis <i>check.</i> 30.03.06 WZ <i>appr.</i>		<i>drawing-no...:</i> MB_32			
<i>dimensioning incl. finish</i>		<i>sheet:</i> 1			
e00	06-0194	S_Krautenbac	24.03.2006	<i>of:</i> 1	
d00	02-0124	A_Nobis	06.10.2003		
c00	01-0266	V_Spitzauer	13.06.2001		
<i>rev. change-no</i> <i>name</i> <i>date</i>		<i>distribution to:</i>		<i>remarks:</i>	
				FE	AZ
				QSM	RMT
				.	.
				X	.